

FEATURES AND BENEFITS

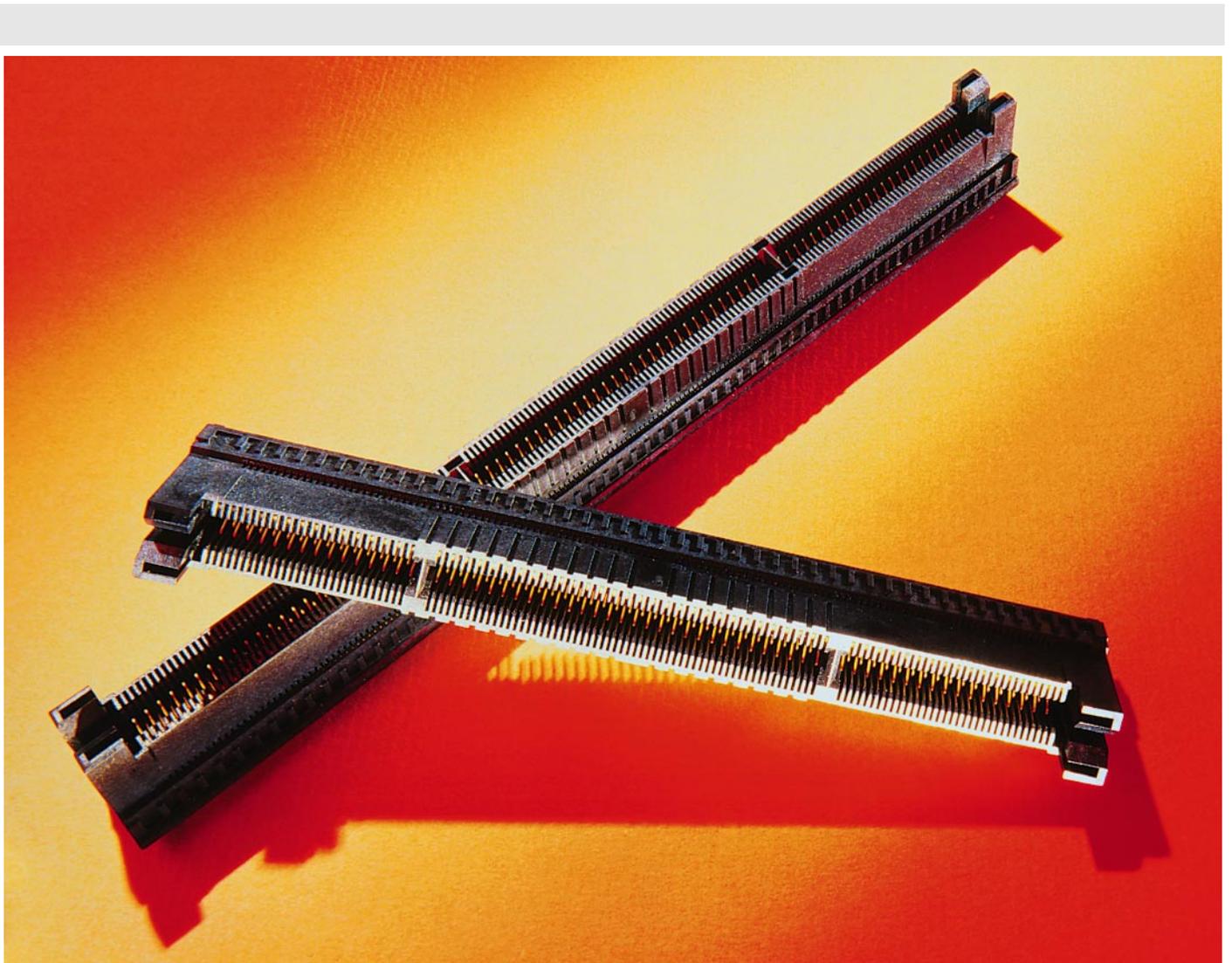
The HiSpecGS connector features Molex's patented Ground by Design™ contact system with two mating levels: longer power/ground contacts and shorter high speed signal contacts. This innovative design offers low insertion force, a shorter signal electrical path, lower inductance and speeds over 400MHz.

Molex's HiSpecGS connector features a 0.76mm (.030") pitch with 32 high speed signals and 34 power/ground contacts per linear inch, enabling its fast edge rate, low cross talk and high performance capabilities. The 330-circuit HiSpecGS connector is used in the Alpha Slot B 21264 processor for WTX platform work stations. Molex and Alpha Processor, Inc., the maker of the Alpha 21264 processor, worked together to develop this interconnect. The 108-circuit and 242-circuit HiSpecGS connectors will be used as the Memory Expansion Card Connector (MECC) for Rambus-based memory cards. The 108-circuit connector is for single channel Rambus applications; the 242-circuit connector is for dual channel Rambus applications.

The Molex HiSpecGS connector series provides exceptional price performance value in a high-density package.



High Speed Edgecard Connector in Ground Signal Format for High Performance Applications



FEATURES AND SPECIFICATIONS

Features and Benefits

- Ground by Design terminals for low insertion force and high speed electrical performance (~400MHz)
- Standard PCB tolerances can be used for less expensive board production
- Surface Mount Compatible
- Ground-signal-ground-signal format provides excellent signal integrity and impedance control
- 108 and 242 circuit connectors for 28Ω systems
- 330 circuit connectors for 50Ω systems

Reference Information

Product Specification: PS-74191
UL File No.: 97129UL
CSA File No.: LR 19980-483

Electrical

Voltage: 30Vrms
Current: Per signal pin—0.5A
Per power pin—1.75A
Contact Resistance: 5mΩ max.
Dielectric Withstanding Voltage: 400V AC
Insulation Resistance: 1000 MΩ min.
Loop Inductance: 108 and 242 Circuit — 2.5nH
Capacitance: 108 and 242 Circuit — 2.6pF

Mechanical

Mating Force: 1.32kg (2.90 lbs.) max. per group of 30 pins
Durability: 50 Cycles

Physical

Housing: Glass-filled LCP, UL 94V-0
Contact: Copper Alloy
Plating: Gold flash over Palladium Nickel, Nickel underplate
Forklock: Phosphor Bronze



HiSpecGS™

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ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.	PC Tail Length	PCB Hold Down
108	74191-0007	2.29 (.090)	2 Forklocks
108	74191-0003	2.92 (.115)	2 Forklocks
242	74191-0005	2.29 (.090)	3 Forklocks
242	74191-0004	2.92 (.115)	3 Forklocks
330	74191-0002	2.92 (.115)	4 Forklocks

Note: Contact Inside Sales for other circuit sizes



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